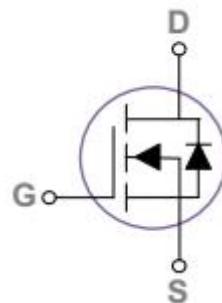


## N-Channel Power MOSFET

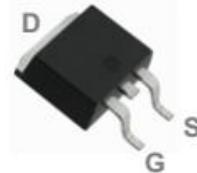
### General Features

- $V_{DS} = 60V, I_D = 17A$   
 $R_{DS(ON)} < 75 \text{ m}\Omega @ V_{GS}=10V$   
 $R_{DS(ON)} < 90 \text{ m}\Omega @ V_{GS}=4.5V$
- Improved dv/dt capability
- High density cell design for ultra low Rdson
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation



### Applications

- Power switching application
- Hard switched and high frequency circuits
- Motor drive



TO252 Pin Configuration

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_c=25^\circ\text{C}$ )	$I_D(25^\circ\text{C})$	17	A
Drain Current-Continuous ( $T_c=100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	12	A
Pulsed Drain Current	$I_{DM}$	44	A
Maximum Power Dissipation	$P_D$	25	W
Derating factor		0.2	$\text{W}/^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-50 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	3.3	°C/W
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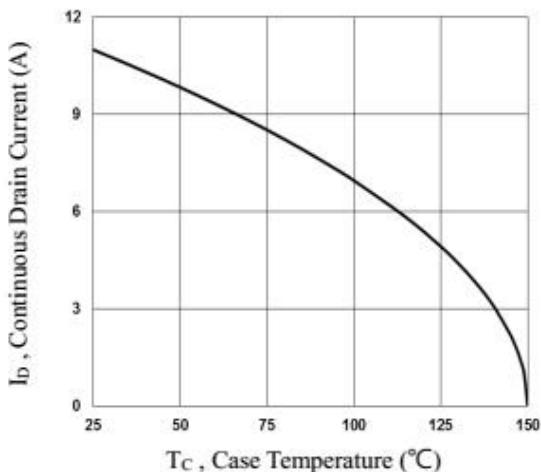
**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.8	2.5	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> = 6A	-	60	75	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A		70	90	
Forward Transconductance	g <sub>F</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =3A	-	4	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	500	725	PF
Output Capacitance	C <sub>oss</sub>		-	45	65	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	16	30	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =1A V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω	-	2.9	6	nS
Turn-on Rise Time	t <sub>r</sub>		-	9.5	18.	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	18.4	35	nS
Turn-Off Fall Time	t <sub>f</sub>		-	5.3	10	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =48V, I <sub>D</sub> =6A, V <sub>GS</sub> =10V	-	9.3	13	nC
Gate-Source Charge	Q <sub>gs</sub>		-	2.1	3	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	1.8	4	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =1A, T <sub>J</sub> = 25°C	-		1.0	V
Diode Forward Current (Note 2)	I <sub>s</sub>	V <sub>G</sub> =V <sub>D</sub> =0V	-	-	11	A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =30V, I <sub>s</sub> = 1A, T <sub>J</sub> =25°C di/dt = 100A/μs <sup>(Note 3)</sup>	-	23.2	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	14.3	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

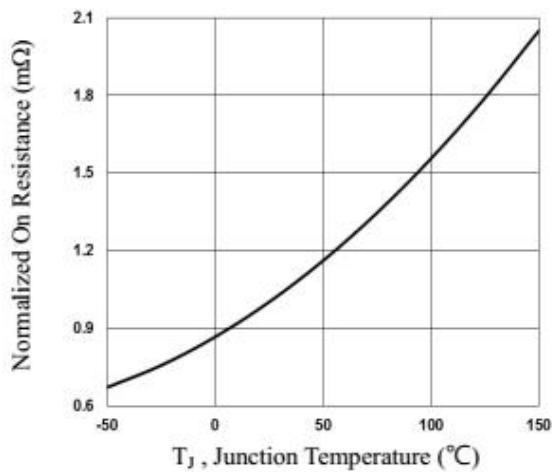
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

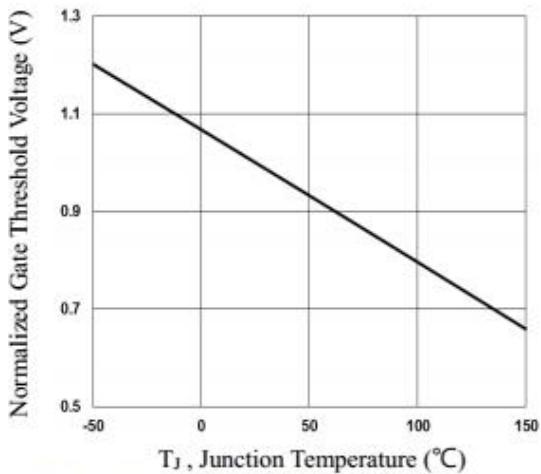
## Typical Electrical and Thermal Characteristics (Curves)



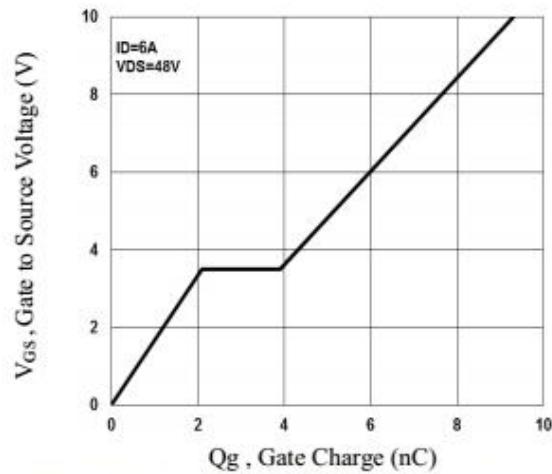
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



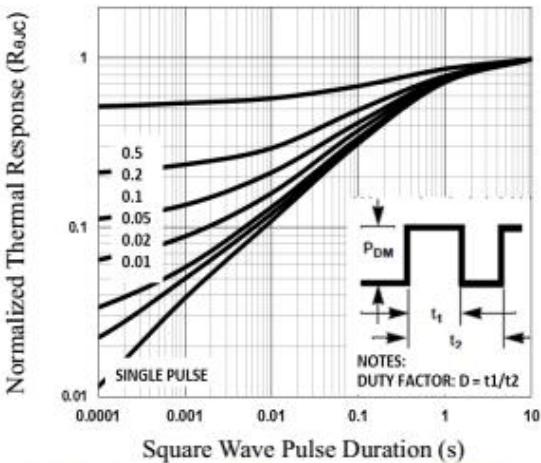
**Fig.2 Normalized RDSON vs. T<sub>j</sub>**



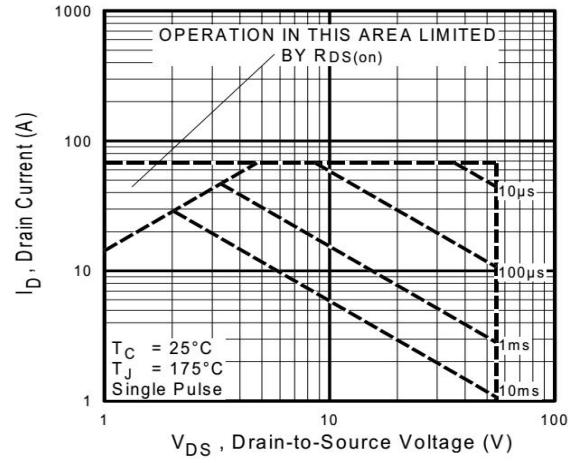
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



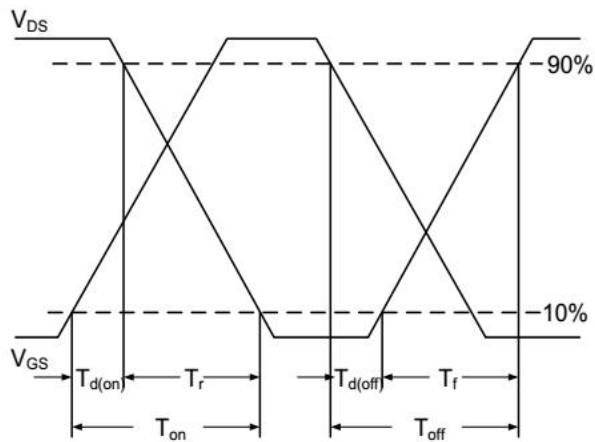
**Fig.4 Gate Charge Characteristics**



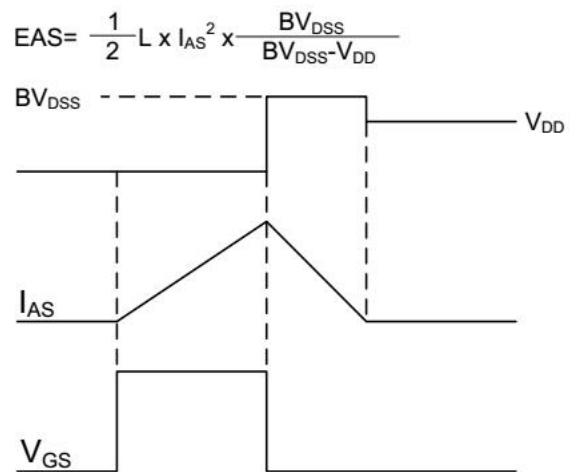
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

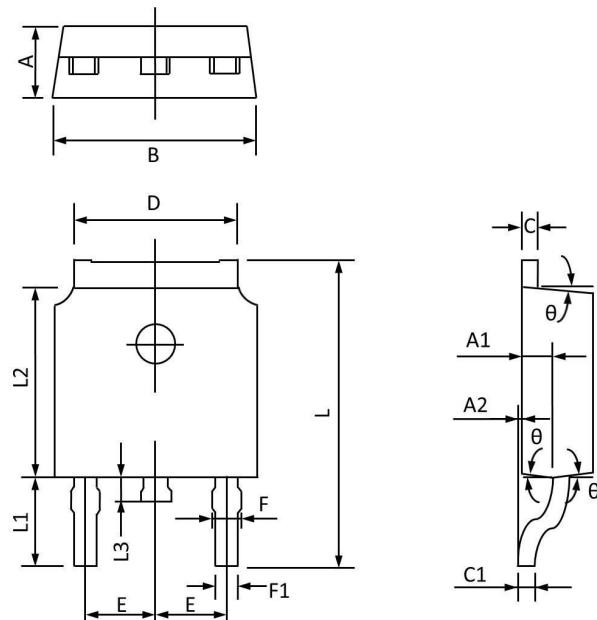


**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## TO252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°